

3. Specifications are subject to change without notice.

SPECIFICATION CSM28Y2CZ

PACKAGE OUTLINES 5.60[0.221] RECOMMENDED PAD LAYOUT 2.15[0.085*] 6.9 [0.272"] + 2.4000.095°J ø1.8 [ø0.071*] 3.9 [0.154"] 4.60 [0.1811] -0.20 [0.008°] 80 [0.071*] CATHODE **+**0.80 [0.032°] Notes: 1. All dimensions are in millimeters (inches). 2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted.

Part Number C		Chip Material	Color of Emission	Lens Type	Viewing Angle		
	CSM28Y2CZ	InGaAIP	Yellow	Water Clear	25°		





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	75	mW	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Toot Condition	Value			Lloit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	630	1500	ı	mcd
Forward Voltage	VF	IF = 20mA	-	2.0	2.5	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	25	-	Deg
Dominant Wavelength	λD	IF = 20mA	-	590	ı	nm

^{*}Tolerance of viewing angle: -10 / +5 deg.



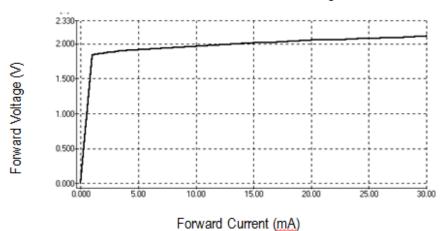


OPTICAL CHARACTERISTIC CURVES

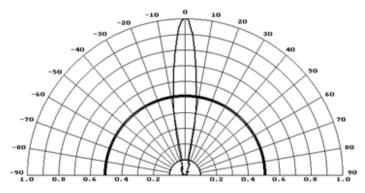
Relative Intensity vs. Wavelength 100 80 60 40 20 300 400 500 600 700 800 900 1000 1100

Forward Current vs. Forward Voltage

Wavelength (nm)



Directive Characteristics

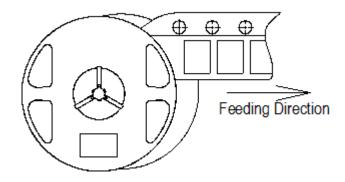


RoHS Compliant

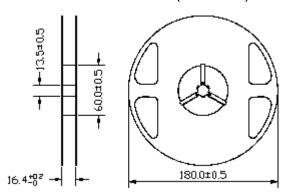


PACKAGING SPECIFICATION

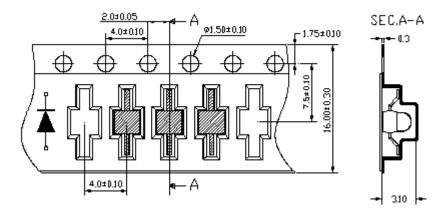
Feeding Direction



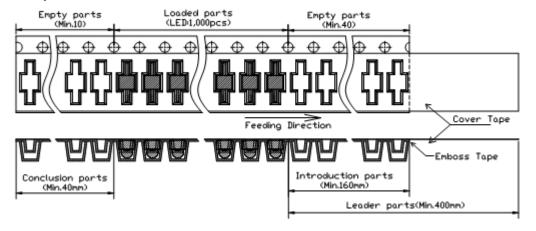
Dimensions of Reel (Unit: mm)



Dimensions of Tape (Unit: mm)



Arrangement of Tape



Notes:

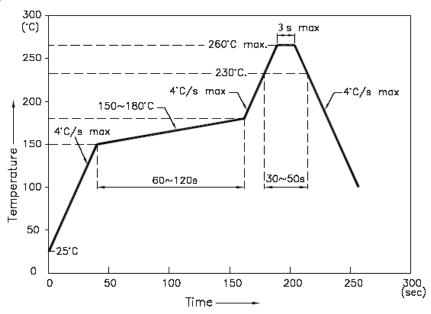
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamp is two;
- 3. The cathode is oriented towards the tape sprocket hole;
- 4. 1,000 pcs/Reel





SOLDERING CONDITIONS

Reflow Temp/Time



Notes:

- 1. We recommend the reflow temperature 245°C (± 5 °C). The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.

Soldering Iron

Basic spec is ≤ 5 sec when 260°C. If temperature is higher, time should be shorter ($\pm 10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230°C.